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(54) **STANDALONE AND SCALABLE COOLING INFRASTRUCTURE**

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(57) **ABSTRACT**

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Multiple systems for providing liquid and closed loop air cooling for Information Technology (IT) components is disclosed. The systems for cooling IT include a first module with at least one dry cooler, a second module with at least one liquid heat exchanger device, and a third module with an air to liquid exchange section that includes at least one air to liquid exchanger that provides air cooling to one or more IT units. The system may also include a fourth module that includes the one or more IT units.

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